

SSR1N60B / SSU1N60B

600V N-Channel MOSFET

General Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar, DMOS technology.

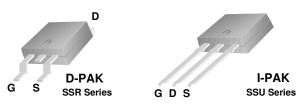
This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supplies.

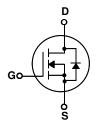
Features

- 0.9A, 600V, $R_{DS(on)} = 12\Omega$ @V_{GS} = 10 V • Low gate charge (typical 5.9 nC)
- Low Crss (typical 3.6 pF)
- Fast switching

I-PAK

- · 100% avalanche tested
- · Improved dv/dt capability





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		SSR1N60B / SSU1N60B	Units
V _{DSS}	Drain-Source Voltage		600	V
I _D	Drain Current - Continuous (T _C = 25°C)	0.9	Α
	- Continuous (T _C = 100°C	C)	0.57	Α
I _{DM}	Drain Current - Pulsed	(Note 1)	3.0	Α
V _{GSS}	Gate-Source Voltage		± 30	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	50	mJ
I _{AR}	Avalanche Current	(Note 1)	0.9	Α
E _{AR}	Repetitive Avalanche Energy	(Note 1)	2.8	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		5.5	V/ns
P _D	Power Dissipation (T _A = 25°C) *		2.5	W
	Power Dissipation (T _C = 25°C)		28	W
	- Derate above 25°C		0.22	W/°C
T _J , T _{stg}	Operating and Storage Temperature Rang	е	-55 to +150	°C
T _L	Maximum lead temperature for soldering p 1/8" from case for 5 seconds	ourposes,	300	°C

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		4.53	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		50	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		110	°C/W

Symbol	Parameter	Test Conditions	S	Min	Тур	Max	Units
Off Cha	aracteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600			V
ΔBV _{DSS} / ΔΤ _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced		0.65		V/°C	
I _{DSS} Zero Gate Voltage Drain Current	7 0	V _{DS} = 600 V, V _{GS} = 0 V				10	μΑ
	V _{DS} = 480 V, T _C = 125°C	2			100	μΑ	
I _{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 30 \text{ V}, V_{DS} = 0 \text{ V}$				100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$				-100	nA
On Cha	racteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 μA		2.0		4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_D = 0.45 \text{ A}$		9.7	12	Ω	
9FS	Forward Transconductance	V _{DS} = 40 V, I _D = 0.45 A	(Note 4)		0.92		S
Dynam i C _{iss}	ic Characteristics Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V,			165	215	pF
C _{oss}	Output Capacitance	f = 1.0 MHz			18	25	pF
C _{rss}	Reverse Transfer Capacitance			3.6	4.7	рF	
Switchi	ing Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{DD} = 300 V, I _D = 1.0 A,			14	40	ns
t _r	Turn-On Rise Time	$R_{G} = 25 \Omega$			45	100	ns
t _{d(off)}	Turn-Off Delay Time	11G = 23 22			25	60	ns
t _f	Turn-Off Fall Time		(Note 4, 5)		35	80	ns
Qg	Total Gate Charge	V _{DS} = 480 V, I _D = 1.0 A,			5.9	7.7	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V			1.0		nC
Q _{gd}	Gate-Drain Charge		(Note 4, 5)		2.7		nC
Drain-S	Source Diode Characteristics a	nd Maximum Rating	s				
I _S	Maximum Continuous Drain-Source Did					0.9	Α
I _{SM}	Maximum Pulsed Drain-Source Diode F	orward Current				3.0	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 0.9 \text{ A}$				1.4	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{S} = 1.0 \text{ A},$			180		ns
Q _{rr}	Reverse Recovery Charge	dl _F / dt = 100 A/μs	(Note 4)		0.47		μС

- **Notes:**1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 115mH, I_{AS} = 0.9A, V_{DD} = 50V, R_G = 25 Ω , Starting T_J = 25°C 3. I_{SD} \leq 1.0A, di/dt \leq 300A/µs, V_{DD} \leq BV_{DSS}, Starting T_J = 25°C 4. Pulse Test : Pulse width \leq 300µs, Duty cycle \leq 2% 5. Essentially independent of operating temperature

Typical Characteristics

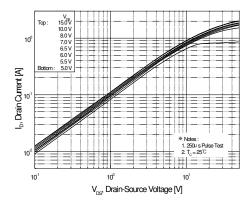


Figure 1. On-Region Characteristics

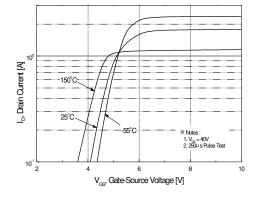


Figure 2. Transfer Characteristics

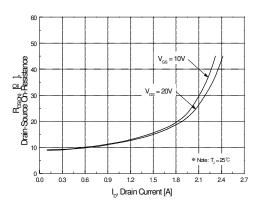


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

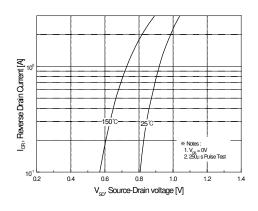


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

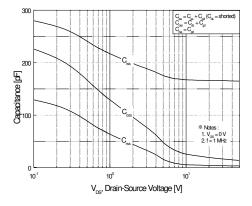


Figure 5. Capacitance Characteristics

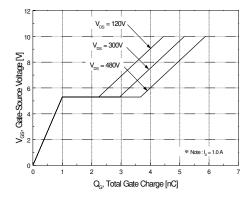


Figure 6. Gate Charge Characteristics

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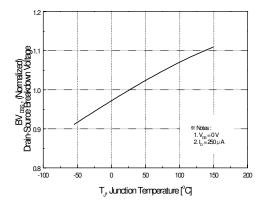


Figure 7. Breakdown Voltage Variation vs Temperature

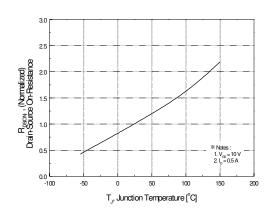


Figure 8. On-Resistance Variation vs Temperature

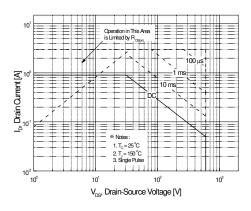


Figure 9. Maximum Safe Operating Area

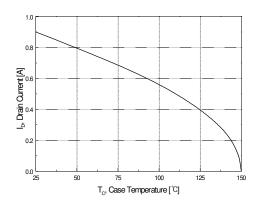


Figure 10. Maximum Drain Current vs Case Temperature

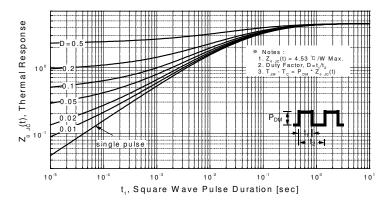
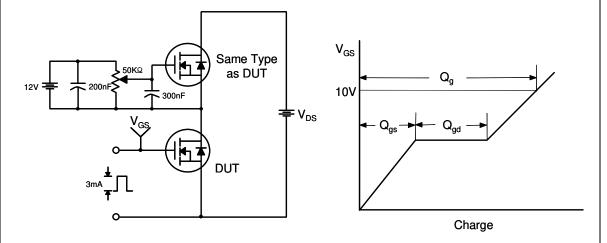


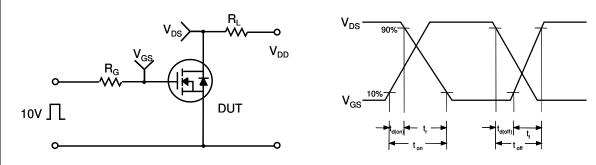
Figure 11. Transient Thermal Response Curve

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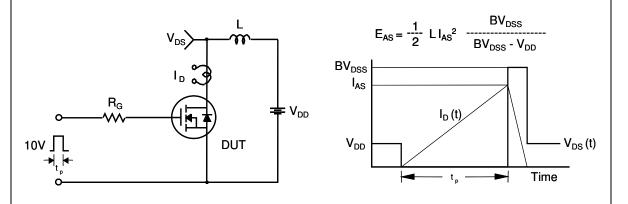
Gate Charge Test Circuit & Waveform



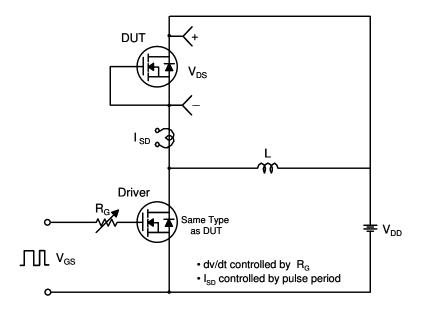
Resistive Switching Test Circuit & Waveforms

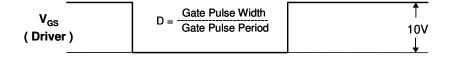


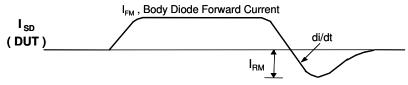
Unclamped Inductive Switching Test Circuit & Waveforms



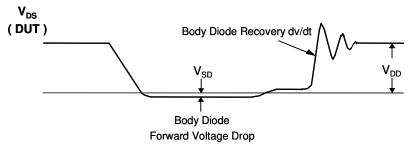
Peak Diode Recovery dv/dt Test Circuit & Waveforms

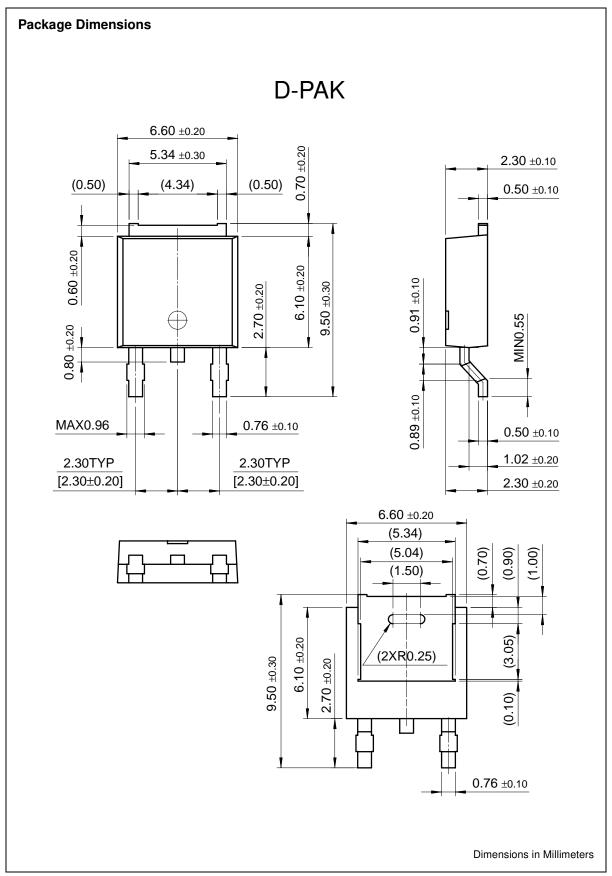


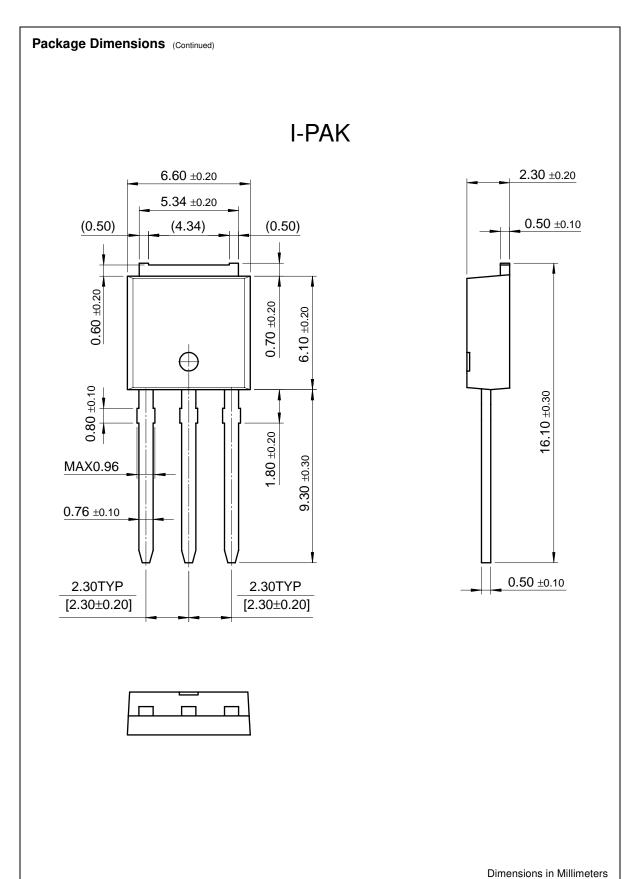




Body Diode Reverse Current







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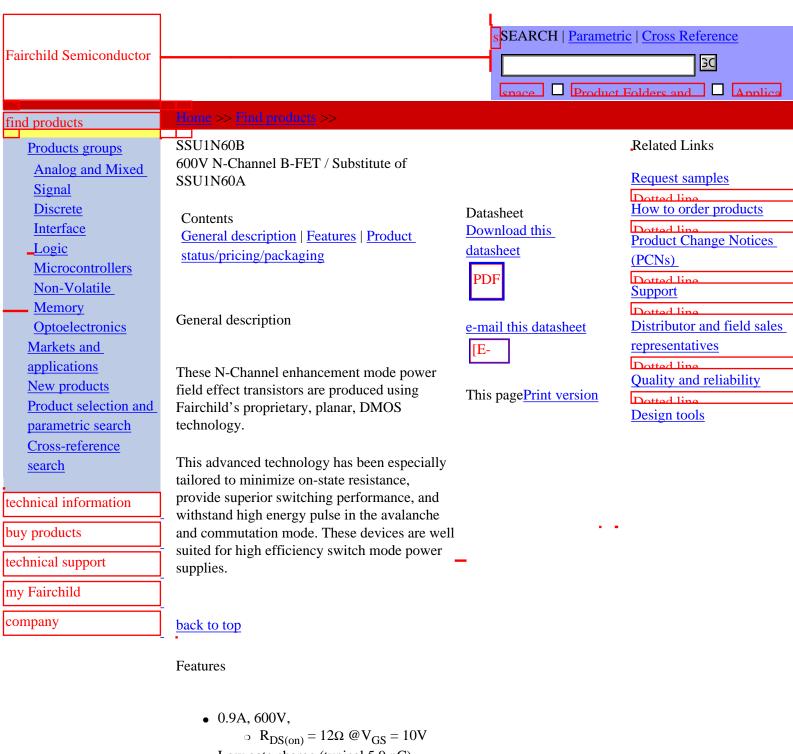
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- Low gate charge (typical 5.9 nC)
- Low Crss (typical 3.6 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

back to top

Product status/pricing/packaging

Product	Product status	Pricing*	Package type	Leads	Packing method
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Product Folder - Fairchild P/N SSU1N60B - 600V N-Channel B-FET / Substitute of SSU1N60A

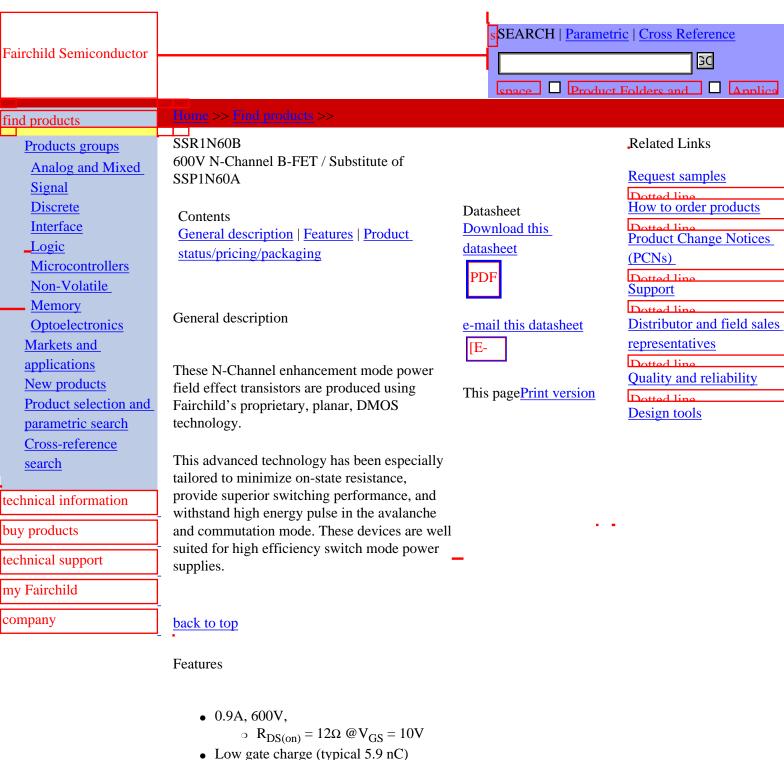
SSU1N60BTU	Full Production	\$0.379	TO-251(IPAK)	3	RAIL

^{* 1,000} piece Budgetary Pricing

back to top

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- Low Crss (typical 3.6 pF)
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back to top

Product status/pricing/packaging

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Product	Product status	Pricing*	Package type	Leads	Packing method

SSR1N60BTM	Full Production	\$0.353	TO-252(DPAK)	2	TAPE REEL
SSR1N60BTF	Full Production	\$0.379	TO-252(DPAK)	2	TAPE REEL

^{* 1,000} piece Budgetary Pricing

back to top

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